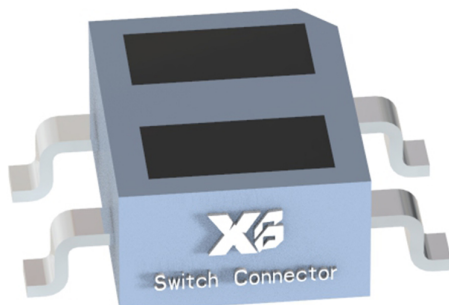




标准&定制开关连接器产品制造商

DONG GUAN XI BANG ELECTRONICS CO., LTD.



ITR8307/L24/TR8

Features

- Fast response time
- High sensitivity
- Cut-Off visible wavelength
- Thin
- Compact
- Pb free
- This product itself will remain within RoHS compliant version.
- Compliance with EU REACH.
- Compliance Halogen Free .(Br <900 ppm ,Cl <900 ppm , Br+Cl < 1500 ppm).

Description

ITR8307-L24/TR8 is a light reflection switch which includes a GaAs IR-LED transmitter and a NPN photo-transistor with a high photosensitive receiver for short distance, operating in the infrared range. Both components are mounted side- by- side in a plastic package.

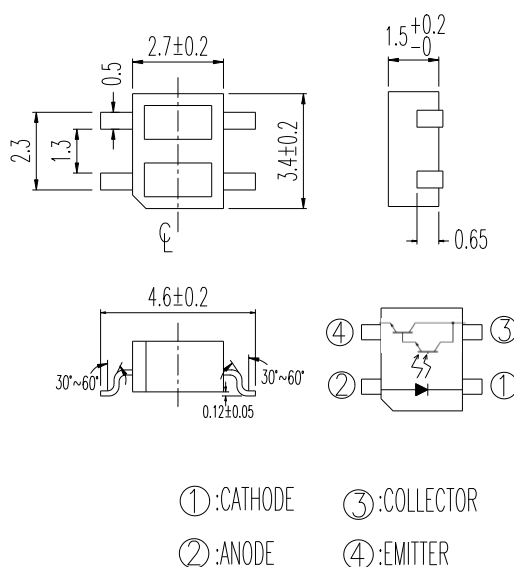
Applications

- Camera
- VCR
- Floppy disk driver
- Cassette type recorder
- Various microcomputer control equipment

Device Selection Guide

Device No.	Chip Material
IR	GaAlAs
PTT	Silicon

Package Dimensions



Absolute Maximum Ratings (Ta=25°C)

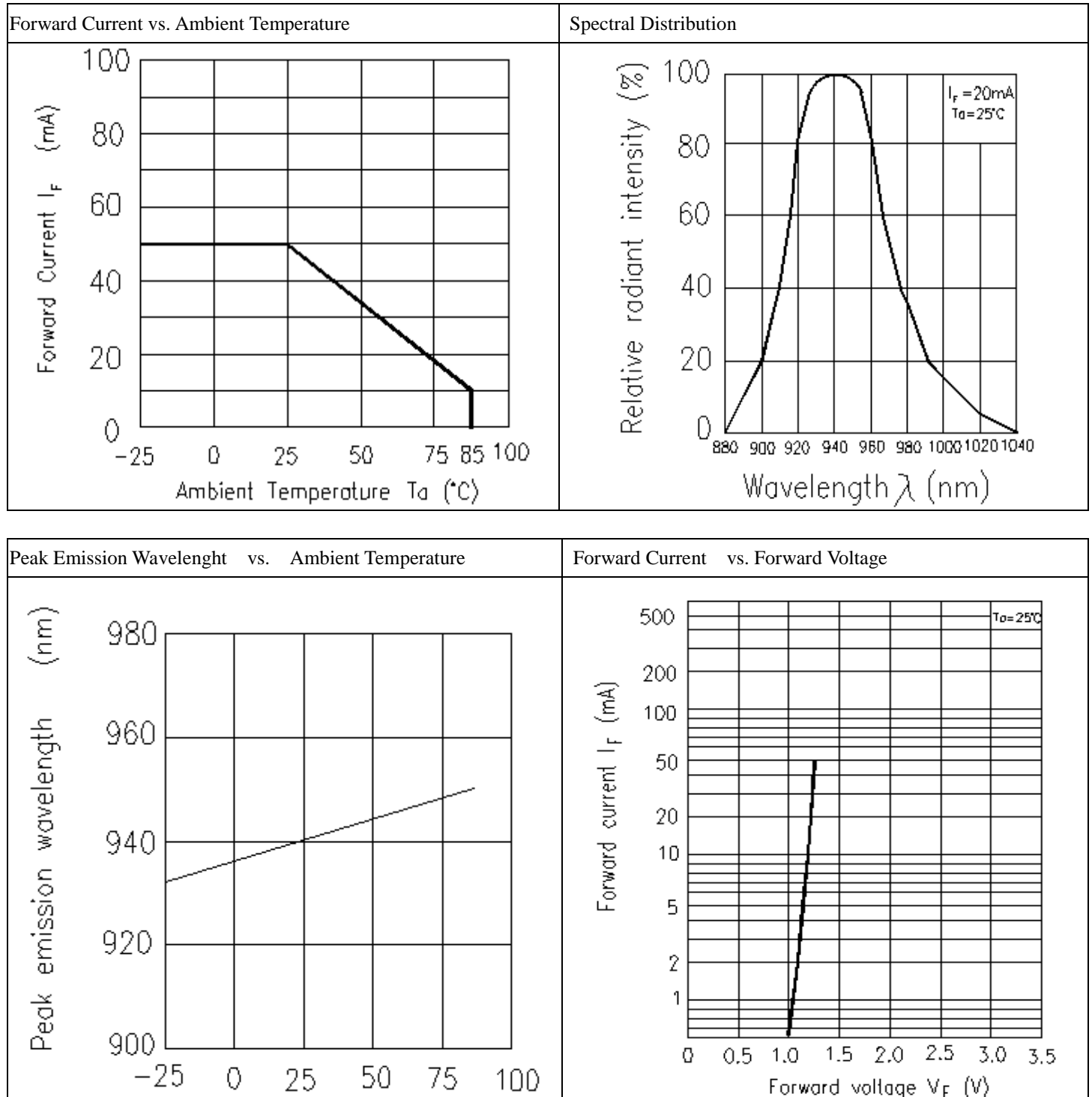
Parameter		Symbol	Rating	Unit
Input	Power Dissipation at(or below) 25°C Free Air Temperature	Pd	75	mW
	Reverse Voltage	V _R	5	V
	Forward Current	I _F	50	mA
	Peak Forward Current (*1) Pulse width ≤100μs, Duty cycle=1%	I _{FP}	1	A
Output	Collector Power Dissipation	P _C	75	mW
	Collector Current	I _C	50	mA
	Collector-Emitter Voltage	B V _{CEO}	30	V
	Emitter-Collector Voltage	B V _{ECO}	5	V
Operating Temperature		Topr	-40~+85	°C
Storage Temperature		Tstg	-40~+90	°C
Lead Soldering Temperature (*2)		Tsol	260	°C

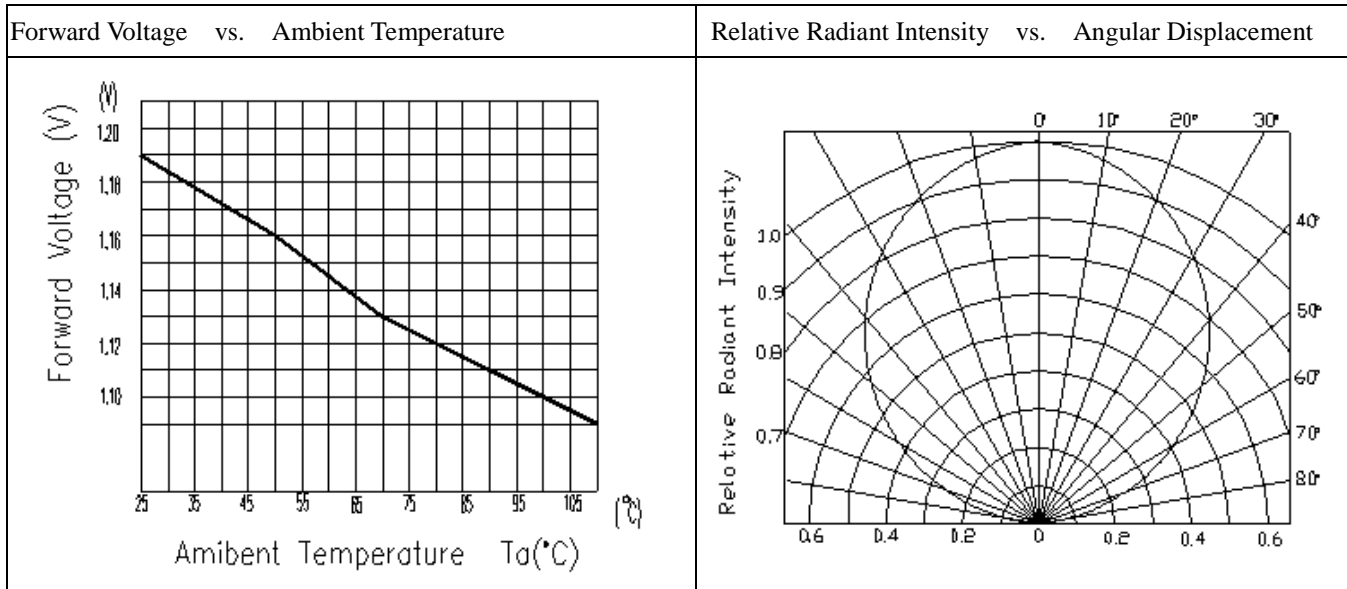
Notes: (* 1) tw=100 μsec. , T=10 msec. (* 2) t=5 Sec

Electro-Optical Characteristics (Ta=25°C)

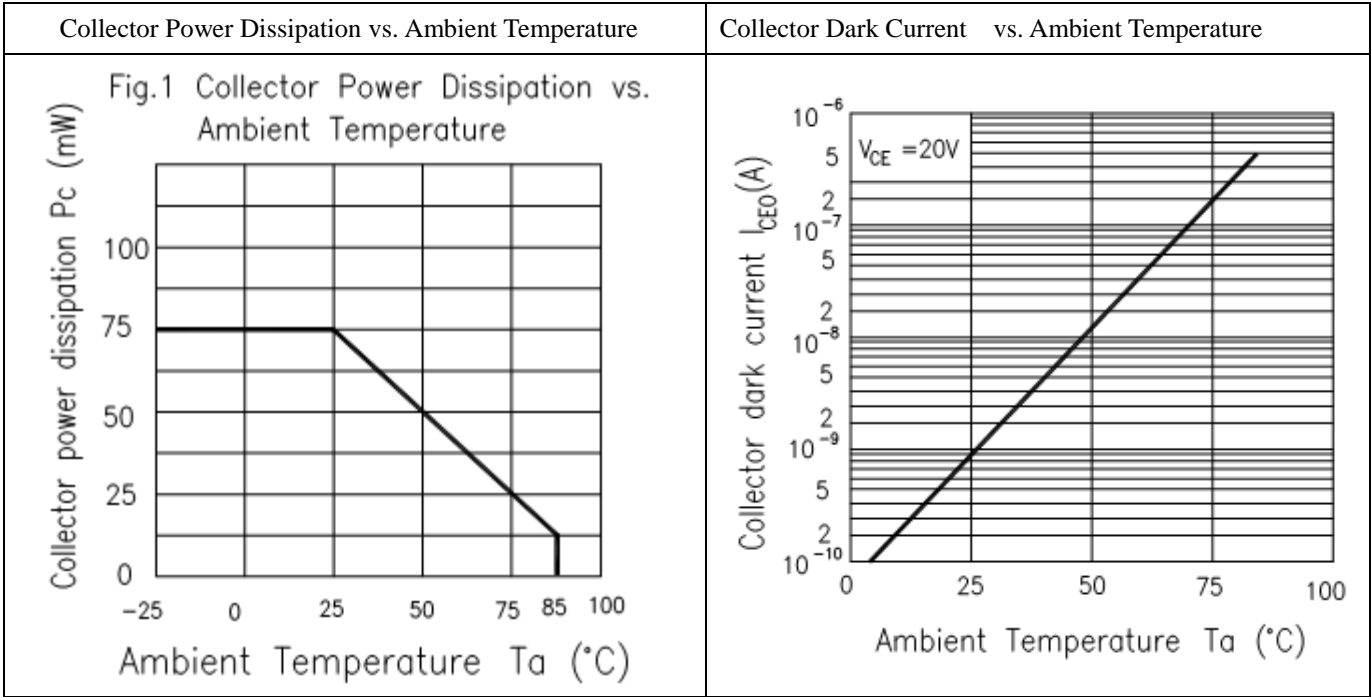
Parameter		Symbol	Min.	Typ.	Max.	Unit	Condition
Input	Forward Voltage	V_F	---	1.2	1.6	V	$I_F=20\text{mA}$
	Reverse Current	I_R	---	---	10	μA	$V_R=5\text{V}$
	Peak Wavelength	λ_p	---	940	---	nm	---
Output	Dark Current	I_{CEO}	---	---	100	nA	$V_{CE}=10\text{V}$
	C-E Saturation Voltage	$V_{CE(sat)}$	---	---	1	V	$I_C=2\text{mA}$ $E_e=1\text{mW/cm}^2$
Transfer Characteristics	Light Current	$I_C(ON)$	0.5	---	15.0	mA	$V_{CE}=2\text{V}$ $I_F=4\text{mA}$
	Leakage Current	I_{CEOD}	---	---	5	μA	$V_{CE}=2\text{V}$ $I_F=4\text{mA}$
	Rise time	t_r	---	20	---	$\mu\text{ sec}$	$V_{CE}=2\text{V}$ $I_C=0.1\text{mA}$ $R_L=1\text{K}\Omega$, $d=1\text{mm}$
	Fall time	t_f	---	20	---	$\mu\text{ sec}$	

Typical Electrical/Optical/Characteristics Curves for IR

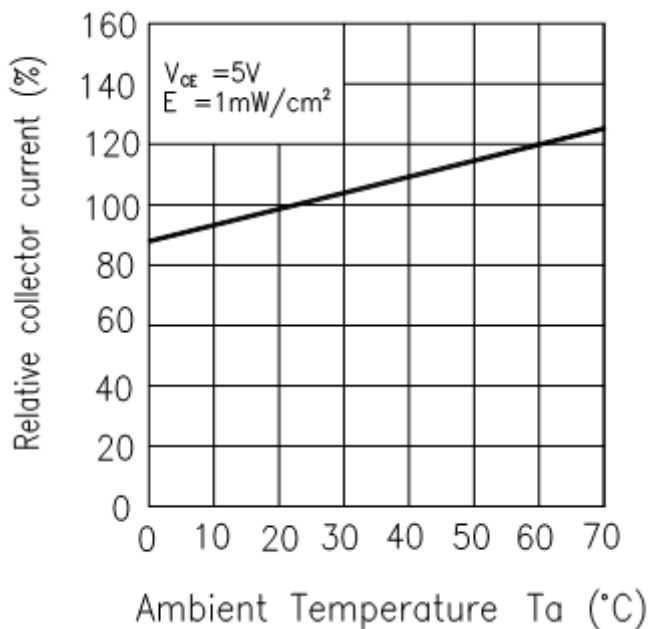




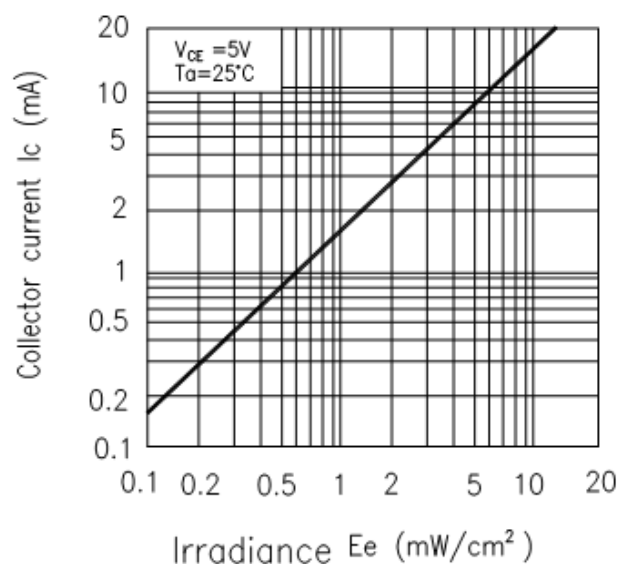
Typical Electro/Optical/Characteristics Curves for PT



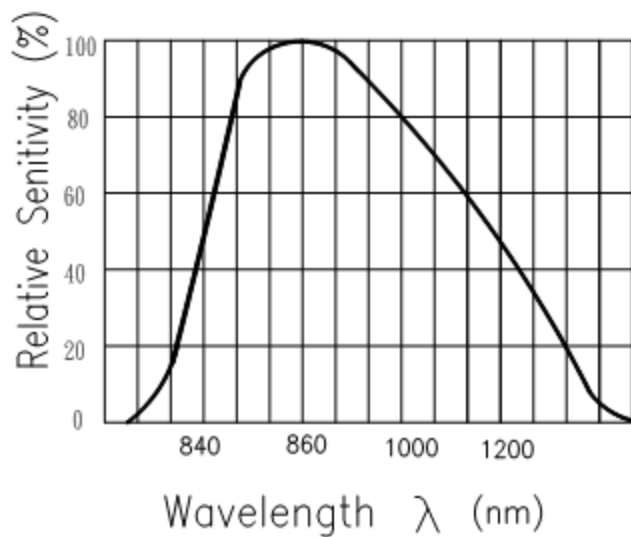
Relative Collector Current vs. Ambient Temperature



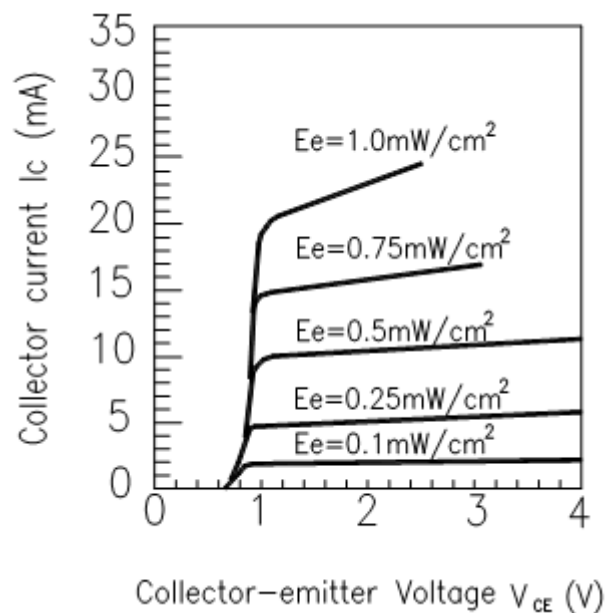
Collector Current vs. Irradiance



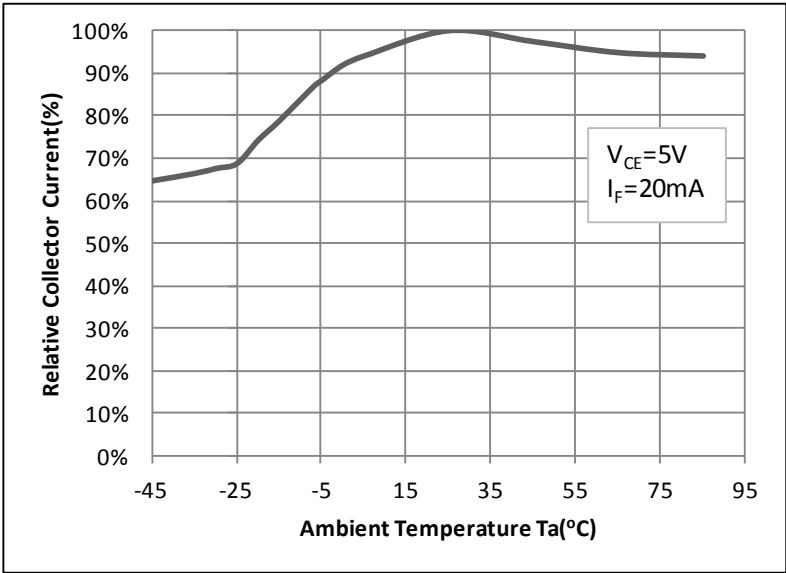
Spectral Sensitivity



Collector Current vs. Collector-emitter Voltage

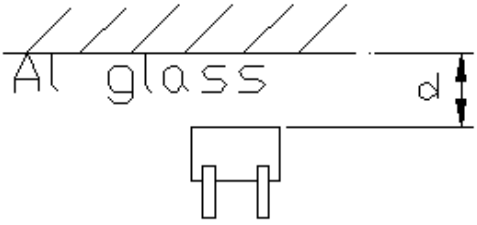
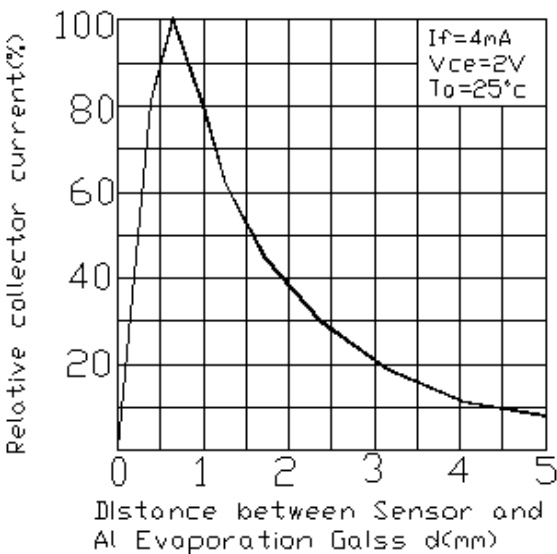


Ambient Temperature vs. Collector Current

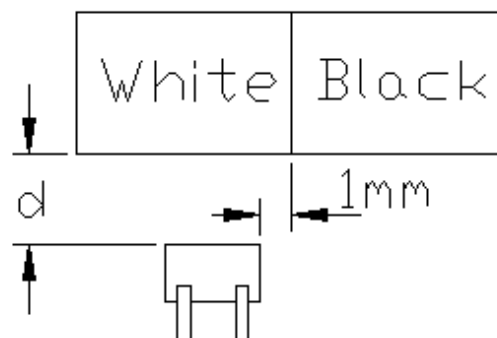
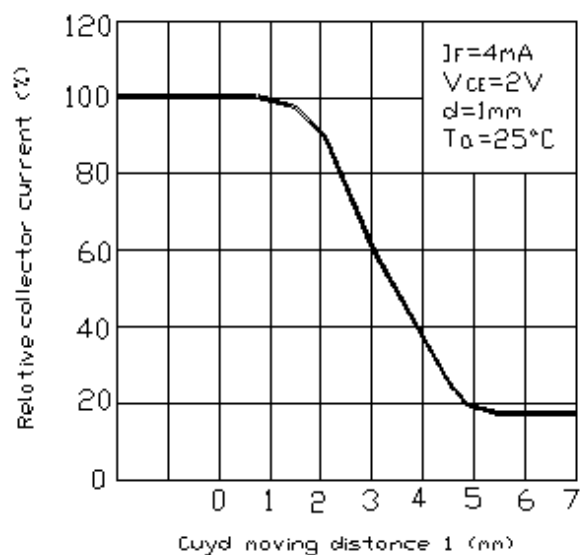


Typical Electrical/Optical/Characteristics Curves For ITR

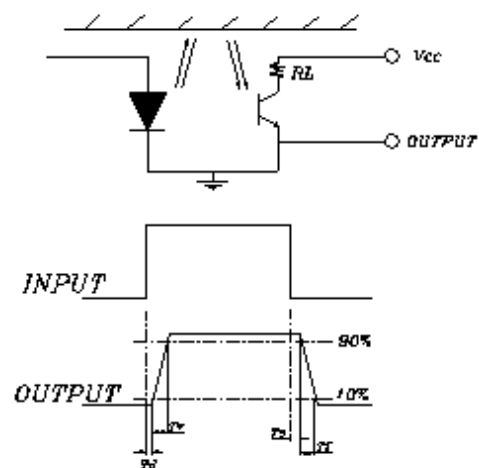
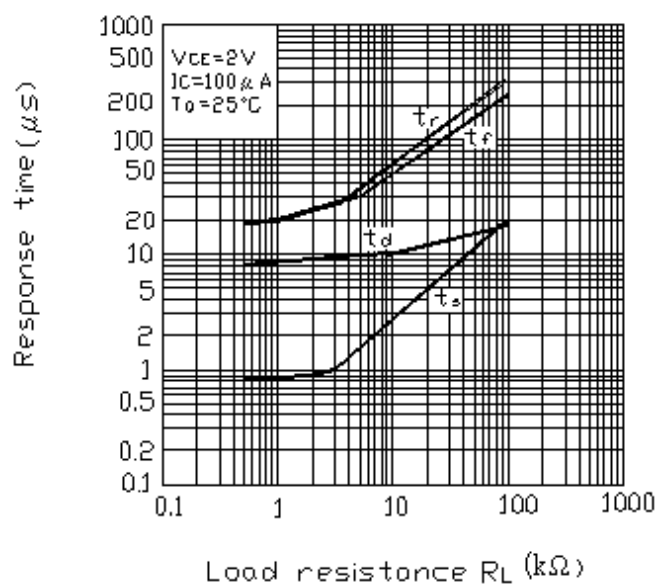
Relative Collector Current vs. Distance between Sensor and AL Evaporation Galss.



Relative Collector Current vs. Card Moving Distance



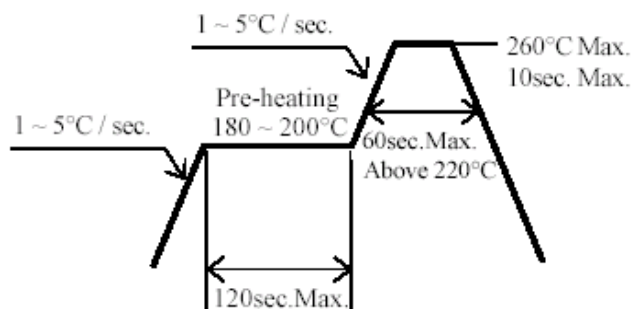
Response Time vs. Load Resistance



Recommended Method of Storage

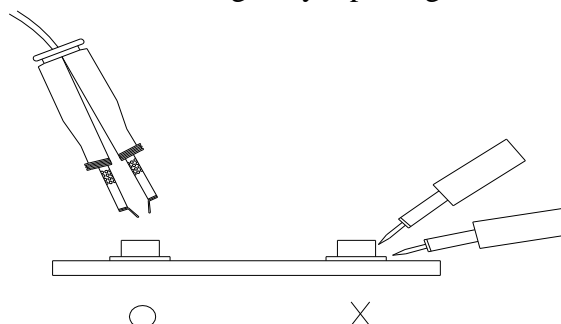
The following are general recommendations for moisture sensitive level (MSL) 4 storage and use:

- Shelf life in sealed bag: 12 months at $< 40^{\circ}\text{C}$ and $< 90\%$ relative humidity (RH)
- After bag is opened, devices that will be subjected to reflow solder or other high temperature process must
 - a) Mounted within 72 hours of factory conditions $< 30^{\circ}\text{C}/60\%\text{RH}$, or
 - b) Stored at $< 20\%$ RH
- Devices require bake, before mounting, if:
Humidity Indicator Card is $> 20\%$ when read at $23 \pm 5^{\circ}\text{C}$
- If baking is required, devices may be baked:
 - a) 192 hours at 40°C , and $< 5\%$ RH (dry air/nitrogen) or
 - b) 96 hours at 60°C , and $< 5\%$ RH for all device containers
 - c) 24 hours at 125°C
- Soldering Condition
 - a) Pb-free solder temperature profile

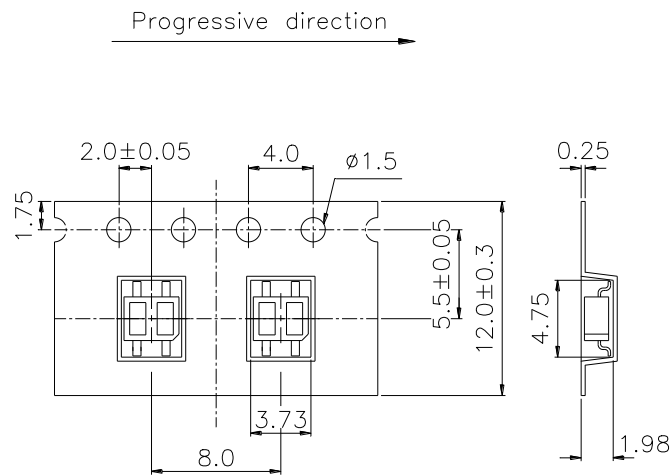


- b) Reflow soldering should not be done more than two times.
 - c) When soldering, do not put stress on the LEDs during heating.
 - d) After soldering, do not warp the circuit board.
- Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.

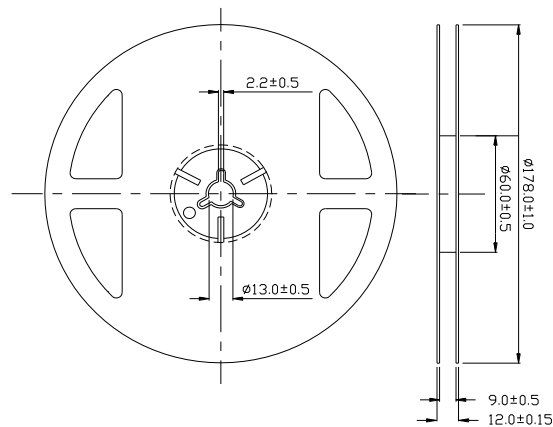


Taping Dimension



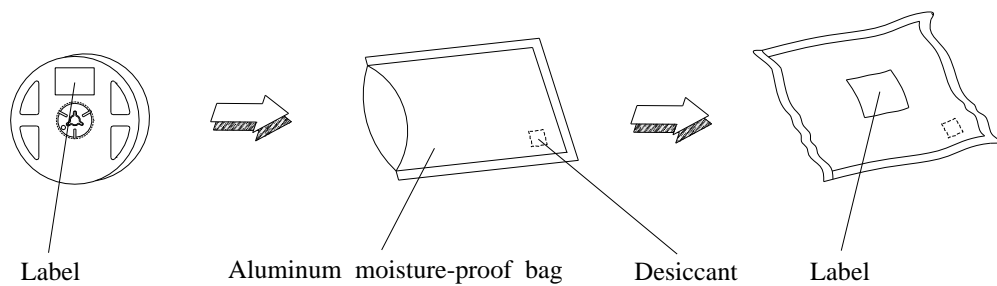
General Tolerance ± 0.1
UNIT:mm

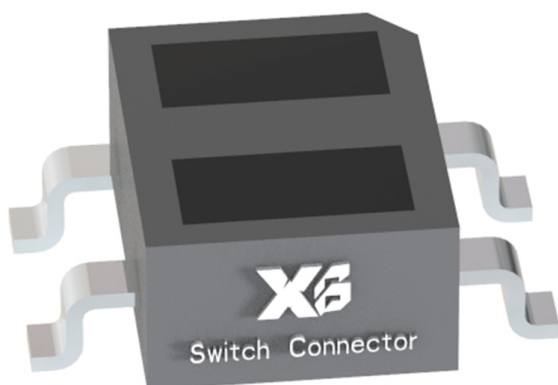
Reel Dimensions



Note: The tolerances unless mentioned is ± 0.1 mm ,Unit = mm

Moisture Resistant Packaging





- CPN: Customer's Product Number
- P/N: Product Number
- QTY: Packing Quantity
- CAT: Luminous Intensity Rank
- HUE: Dom. Wavelength Rank
- REF: Forward Voltage Rank
- LOT No: Lot Number
- X: Month
- Reference: Identify Label Number

DISCLAIMER

- 1.XI BNANG reserves the right(s) on the adjustment of product material mix for the specification.
- 2.The product meets XI BNANG published specification for a period of twelve (12) months from date of shipment.
- 3.The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.
- 4.When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. XI BNANG assumes no responsibility for any damage resulting from the use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
- 5.These specification sheets include materials protected under copyright of XI BNANG. Reproduction in any form is prohibited without obtaining XI BNANG's prior consent.
- 6.This product is not intended to be used for military , aircraft , automotive , medical , life sustaining or life saving applications or any other application which can result in human injury or death. Please contact authorized XI BNANG sales agent for special application request.